

# USB046A

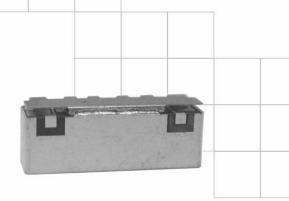
# Band 46 USB Series TDD Bandpass Filter

#### **Features**

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

## **Applications**

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for up to 5.0W at the antenna port.



Part Dimensions: 25.9 × 4.2 × 6.7 mm • 1.7 g

Materials: Ag plated ceramic block with tin plated brass shield

## Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

## **Electrical Specifications**

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	8.0 Watt max
Peak Input Power	-	-	-	80 Watt max
Input-Output Response				
Passband Insertion Loss (20 MHz avg)	5150 - 5925		1.6 dB max	1.6 dB max
Passband Ripple	5150 - 5925	0.8 dB	1.0 dB max	1.0 dB max
Passband Return Loss	5150 - 5925	14 dB	12 dB min	12 dB min
Attenuation:	1 - 4700		55 dB min	55 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification A	<u>llowance</u>
Insertion Loss	0.1 dB
Return Loss	1.0 dB
Attenuation	1.0 dB

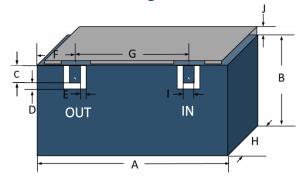
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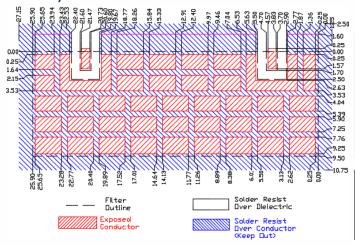




## **Mechanical Drawing**



#### **PCB Layout**



# Packaging and Marking

Dimensio	on Unit	s Spec.	Product	Marking
Reel Diame	eter mm	330		TS
Reel Weig	ht kg	5.5	_	46
Reel Quant		500	YV	VW
PoMM/(Inches)	CustomerF	eed Direction	Wo MM/(Inches)	Bo MM/(Incl Ko MM/(Inches)
\\\	V 8	D		
$W_{o}$	$A_{o}$	Bo	Ko	Po
1.732 in	0.165 in	1.028 in	0.283 in	0.472 in
44.0 mm	4.20 mm	26.10 mm	7.20 mm	12.0 mm

#### Nominal Tolerance Dim. (±mm or Max) (mm) Α 25.90 max 2.90 В max C 1.70 0.13 D 0.80 0.13 E 0.80 0.13 F 4.20 0.13 G 16.90 0.13 Н 6.70 max 1 1.00 0.13 1.10 0.20

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

NOTE: The width of 9.50mm is necessary to support frequencies as low as 1885MHz for Band 39. If only higher frequency TDD bands are supported, then a smaller space can be allocated on the layout.

#### **Electrical Response**

